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High speed Driver with bootstrapping for dual Power MOSFETs



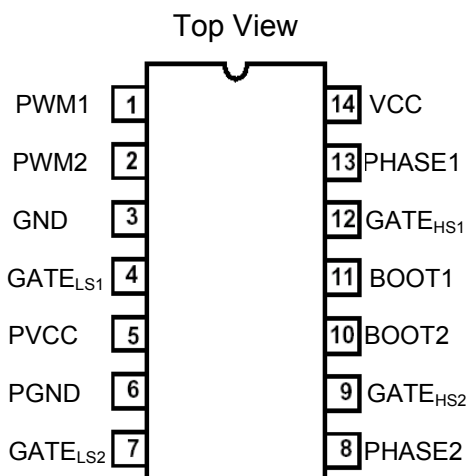
P-DSO-14-3

Features

- Fast rise and fall times for frequencies up to 2 MHz
- Capable of sinking more than 4 A peak current for lowest switching losses
- Charges the High Side and Low Side MOSFET's gate to 5..12 V according to PVCC setting.
- Adjustable High Side and Low Side MOSFET gate drive voltage via PVCC pin for optimizing ON losses and gate drive losses
- Integrates the bootstrap diode for reducing the part count
- Prevents from cross-conducting by adaptive gate drive control
- High voltage rating on Phase node
- Supports shut-down mode for very low quiescent current through three-state input
- Compatible to standard PWM controller ICs (Intersil, Analog Devices)
- Floating High Side MOSFET drive
- Ideal for multi-phase Desktop CPU supplies on motherboards and VRM's

Type	Package	Marking	Ordering Code
TDA21102	P-DSO-14-3	21102	Q67042-S4244

Pinout & Description



Number	Name	Description
1	PWM1	Input for the PWM1 controller signal
2	PWM2	Input for the PWM2 controller signal
3	GND	Ground
4	GATE _{LS1}	Gate drive output for the N-Channel Low Side MOSFET 1.
5	PVCC	Input to adjust the High Side gate drive
6	PGND	Power ground return for the Low Side Drivers
7	GATE _{LS2}	Gate drive output for the N-Channel Low Side MOSFET 2.
8	PHASE2	To be connected to the junction of the High Side and the Low Side MOSFET 2
9	GATE _{HS2}	Gate drive output for the N-Channel High Side MOSFET 2.
10	BOOT2	Floating bootstrap pin. To be connected to the external bootstrap capacitor to generate the gate drive voltage for the High Side N-Channel MOSFET 2.
11	BOOT1	Floating bootstrap pin. To be connected to the external bootstrap capacitor to generate the gate drive voltage for the High Side N-Channel MOSFET 1.
12	GATE _{HS1}	Gate drive output for the N-Channel High Side MOSFET 1.
13	PHASE1	To be connected to the junction of the High Side and the Low Side MOSFET 1
14	VCC	Supply Voltage

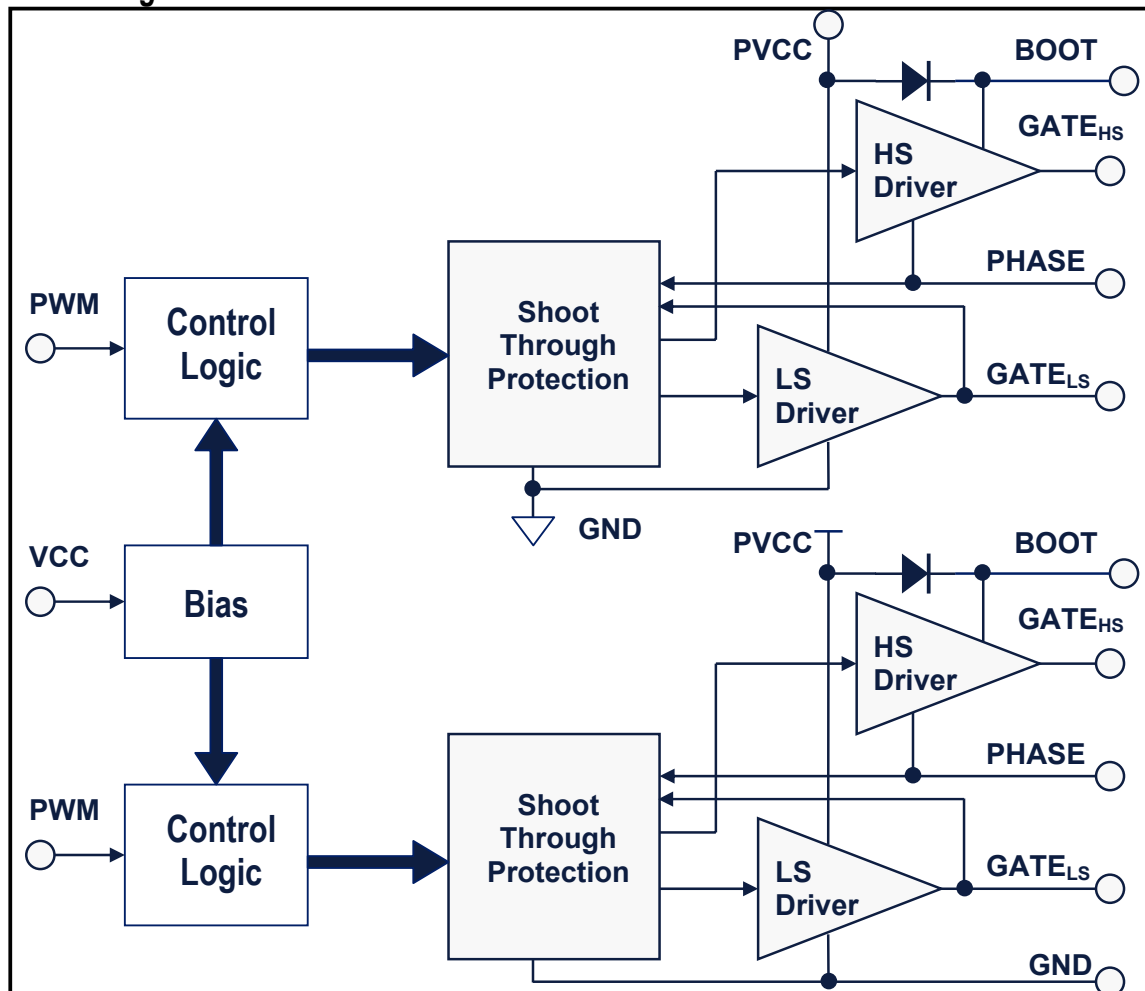
General Description

The dual high speed driver is designed to drive a wide range of N-Channel low side and N-Channel high side MOSFETs with varying gate charges. It has a small propagation delay from input to output, short rise and fall times and the same pin configuration as the HIP6602B. In addition it provides several protection features as well as a shut down mode for efficiency reasons. The high breakdown voltage makes it suitable for mobile applications.

Target application

The dual high speed driver is designed to work well in half-bridge type circuits where dual N-Channel MOSFETs are utilized. A circuit designer can fully take advantage of the driver's capabilities in high-efficiency, high-density synchronous DC/DC converters that operate at high switching frequencies, e.g. in multi-phase converters for CPU supplies on motherboards and VRM's but also in motor drive and class-D amplifier type applications.

Block Diagram



Absolute Maximum Ratings

 At $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value		Unit	
		Min.	Max.		
Voltage supplied to 'VCC' pin	V_{VCC}	-0.3	25	V	
Voltage supplied to 'PVCC' pin	V_{PVCC}	-0.3	25		
Voltage supplied to 'PWM' pin	V_{PWM}	-0.3	5.5		
Voltage supplied to 'BOOT' pin referenced to 'PHASE'	$V_{BOOT} - V_{PHASE}$	-0.3	25		
Voltage rating at 'PHASE' pin, DC	V_{PHASE}	-1	25		
Voltage rating at 'PHASE' pin, $t_{pulse_max} = 500\text{ns}$ Max Duty Cycle = 2%		-20	30		
Voltage supplied to $GATE_{HS}$ pin referenced to 'PHASE' $T_{pulse_max} < 100\text{ns}$, $E < 2\mu\text{J}$	V_{GATEHS}	-3.5	$V_{BOOT} + 0.3$		
Voltage supplied to $GATE_{LS}$ pin referenced to 'GND' $T_{pulse_max} < 100\text{ns}$, $E < 2\mu\text{J}$	V_{GATELS}	-5	$V_{VCC} + 0.3$		
Junction temperature	T_J	-25	150		°C
Storage temperature	T_S	-55	150		
ESD Rating; Human Body Model			4	kV	
IEC climatic category; DIN EN 60068-1			55/150/56	-	

Thermal Characteristic

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction-solder joint (pin 4)	Rth-JS		40.5		K/W
Thermal resistance, junction-case	Rth-JC		44.7		
Thermal resistance, junction-ambient	Rth-JA		116.2		

Electrical Characteristic

 At $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Supply Characteristic						
Bias supply current	I_{VCC}	$f = 1\text{ MHz}$, NO LOAD $V_{PVCC} = V_{VCC} = 12\text{ V}$		1.3	1.8	mA
Quiescent current	I_{VCCQ}	$1.8\text{ V} \leq V_{PWM} \leq 3.0\text{ V}$		3.8	4.9	
Power supply current	I_{PVCC}	$f = 1\text{ MHz}$, NO LOAD $V_{PVCC} = V_{VCC} = 12\text{ V}$		25	33	
Under-voltage lockout		V_{VCC} rising threshold	9.7	10.1	10.5	V
Under-voltage lockout		V_{VCC} falling threshold	7.3	7.6	8.0	V
Input Characteristic						
Current in 'PWM' pin	I_{PWM_L}	$V_{PWM} = 0.4\text{ V}$	-80	115	-150	μA
Current in 'PWM' pin	I_{PWM_H}	$V_{PWM} = 4.5\text{ V}$	120	180	250	
Shut down window	V_{IN_SHUT}	$t_{SHUT} > 350\text{ ns}$	1.7		3.1	V
Shut down hold-off time	t_{SHUT}	$1.7\text{ V} \leq V_{PWM} \leq 3.1\text{ V}$	100	200	320	ns
PWM pin open	V_{PWM_O}		1.8	2.0	2.2	V
PWM Low level threshold (falling)	V_{PWM_L}				1.4	
PWM High level threshold (rising)	V_{PWM_H}		3.7			
Pulse Width High Side	t_p	= Pulse with on PWM pin	40			ns

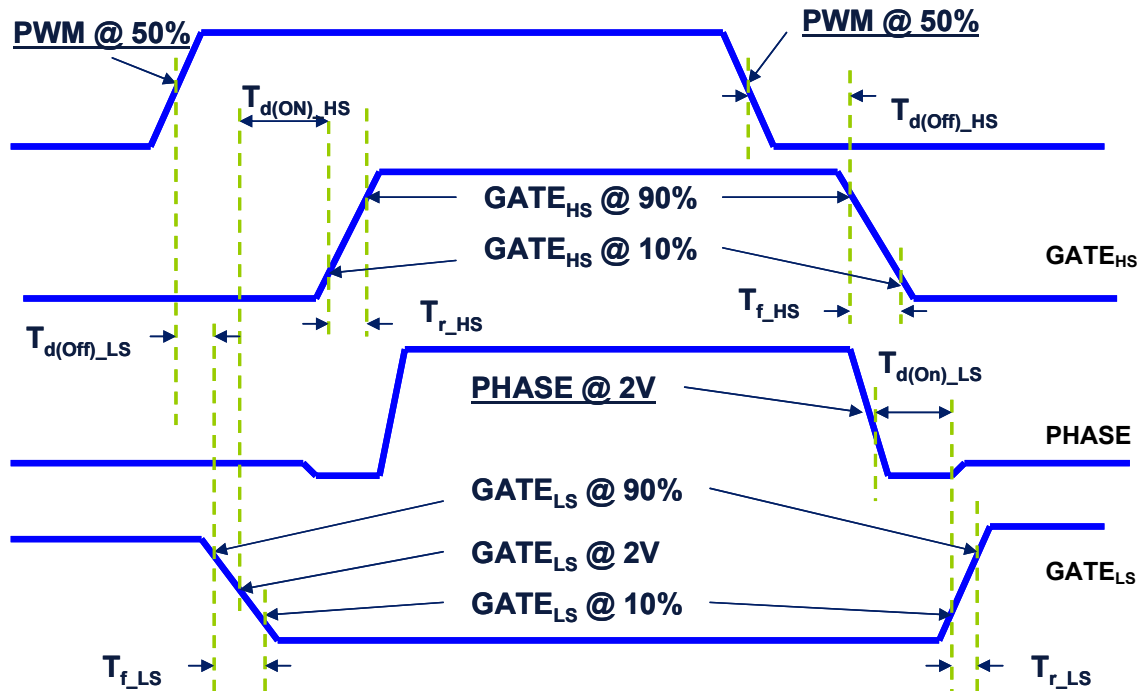
 At $T_j = 25\text{ °C}$, unless otherwise specified

Dynamic Characteristic						
Turn-on propagation Delay High Side*	$t_{d(ON)_HS}$	$P_{PVCC} = V_{VCC} = 12\text{ V}$ $C_{ISS} = 3000\text{ pF}$		18	35	ns
Turn-off propagation delay High Side	$t_{d(OFF)_HS}$			18	25	
Rise time High Side	t_{r_HS}			14	28	
Fall time High Side	t_{f_HS}			14	22	
Turn-on propagation Delay Low Side	$t_{d(ON)_LS}$			17	23	
Turn-off propagation delay Low Side	$t_{d(OFF)_LS}$			14	20	
Rise time Low Side	t_{r_LS}			22	29	
Fall time Low Side	t_{f_LS}			14	22	

At $T_j = 125\text{ °C}$, unless otherwise specified

Dynamic Characteristic					
Turn-on propagation Delay High Side*	$t_{d(ON)_{HS}}$	$P_{PVCC} = V_{VCC} = 12\text{ V}$ $C_{ISS} = 3000\text{ pF}$		22	ns
Turn-off propagation delay High Side	$t_{d(OFF)_{HS}}$			22	
Rise time High Side	$t_{r_{HS}}$			16	
Fall time High Side	$t_{f_{HS}}$			16	
Turn-on propagation Delay Low Side	$t_{d(ON)_{LS}}$			20	
Turn-off propagation delay Low Side	$t_{d(OFF)_{LS}}$			18	
Rise time Low Side	$t_{r_{LS}}$			23	
Fall time Low Side	$t_{f_{LS}}$			16	

Measurement Timing diagram



Operating Conditions

At T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Voltage supplied to 'VCC' pin	V _{VCC}		10.8		13.2	V
Voltage supplied to 'PVCC' pin	V _{PVCC}		5		13.2	V
Input signal transition frequency	f		0.1		2	MHz
Power dissipation	P _{TOT}	T _A = 25 °C, T _J = 125 °C		0.9		W
Junction temperature	T _J		-25		150	°C

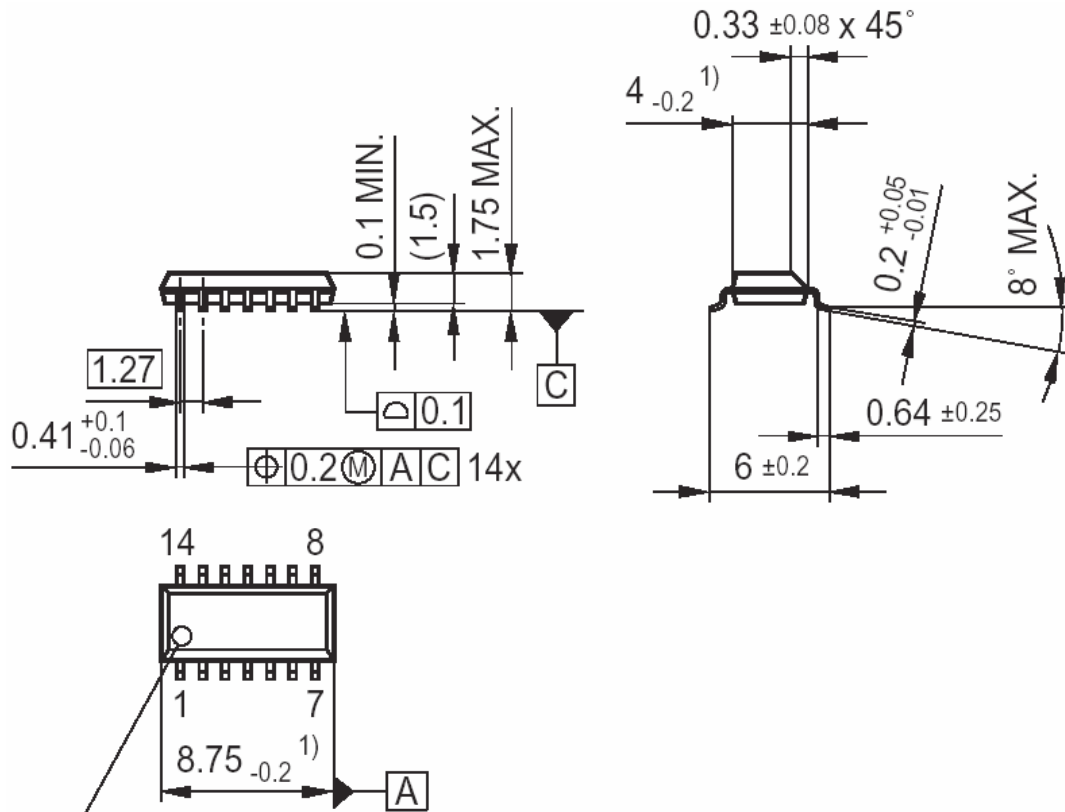
At T_j = 25 °C, unless otherwise specified

Parameter	Conditions	Values			Unit	
		Min.	Typ.	Max.		
Output Characteristic High Side (HS) and Low Side (LS), ensured by design						
Output Resistance	HS; Source	P _{PVCC} = V _{VCC} = 12 V I _{HS_SRC} = 2 A		1 ⁽¹⁾		Ω
	HS; Sink	V _{VCC} = 12 V, P _{PVCC} = 5V		1	1.3	Ω
	HS; Sink	P _{PVCC} = V _{VCC} = 12 V		0.9	1.2	Ω
	LS; Source	P _{PVCC} = V _{VCC} = 12 V I _{HS_SRC} = 2 A		1.4 ⁽²⁾		Ω
	LS; Sink	V _{VCC} = 12 V, P _{PVCC} = 5V		1	1.3	Ω
	LS; Sink	P _{PVCC} = V _{VCC} = 12 V		1	1.25	Ω
Peak output-current	HS; Source	P _{PVCC} = V _{VCC} = 12 V	4			A
	HS; Sink	t _{P_HS} / Pulse < 20 ns	4			
	LS; Source	t _{P_LS} / Pulse < 40 ns	4			
	LS; Sink	D _{HS} < 2%, D _{LS} < 4%	4			

¹ Incremental resistance V_{BOOT}-V_{HS}=4.3V @ I_{SOURCE}=2A

² Incremental resistance V_{VCC}-V_{LS}=4.4V @ I_{SOURCE}=2A

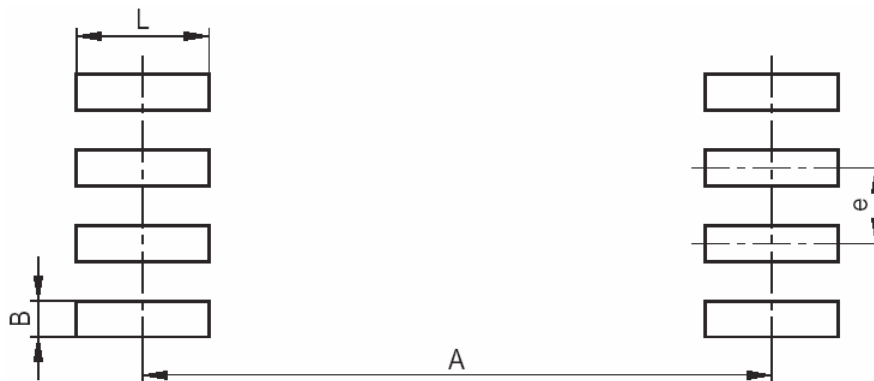
Package Drawing P-DSO-14-3



Index Marking

1) Does not include plastic or metal protrusion of 0.15 max. per side

Layout Footprints



e	A	L	B
1,27 mm	5,69 mm	1,31 mm	0,65 mm



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